ABSTRACT OF THE DISCLOSURE

A method for manufacturing micro electro-mechanical systems includes forming an insulation layer on an upper surface of a semiconductor substrate, forming a structure layer on an upper surface of the insulation layer and etching the structure layer, forming an under bump metal on a predetermined position of an upper surface of the structure layer, forming a via hole in a glass substrate corresponding to the position of the under bump metal and in a shape such that the via hole is larger in diameter at an upper surface of the glass substrate, wherein the glass substrate is bonded to the upper surface of the structure layer and creates a vacuum chamber that protects a structure of the structure layer, and arranging a solder ball in the via hole and bonding the solder ball to the under bump metal.